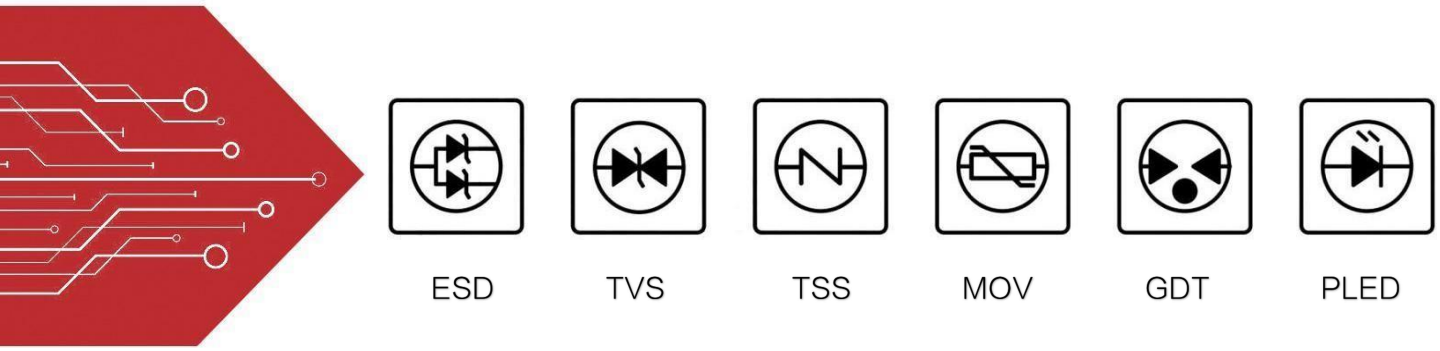
MSKSEMI
SEMICONDUCTOR



Product data sheet

www.msksemi.com

SM4001PL THRU SM4007PL

FEATURES

- Glass passivated device
- Ideal for surface mouted applications
- Low reverse leakage
- Metallurgically bonded construction
- High temperature soldering guaranteed: 250℃/10 seconds,0.375”(9.5mm) lead length, 5 lbs. (2.3kg) tension

MECHANICAL DATA

Case: JEDEC SOD-123FL molded plastic body over passivated chip
Terminals: Solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight:0.0007 ounce, 0.02 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

	P/N	SM4001 PL	SM4002 PL	SM4003 PL	SM4004 PL	SM4005 PL	SM4006 PL	SM4007 PL	UNITS
	MARK	A1	A2	A3	A4	A5	A6	A7	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	VOLTS
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at T_A=65℃ (NOTE 1)	$I_{(AV)}$	1.0							Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) T_L=25℃	I_{FSM}	25.0							Amps
Maximum instantaneous forward voltage at 1.0A	V_F	1.0							Volts
Maximum DC reverse current T_A=25℃ at rated DC blocking voltage T_A=125℃	I_R	10.0 50.0							μA
Typical junction capacitance (NOTE 2)	C_J	4							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	180							K/W
Operating junction and storage temperature range	T_J,T_{STG}	-55 to +150							C°

Note: 1.Averaged over any 20ms period.
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3. Thermal resistance from junction to ambient at 0.375” (9.5mm)lead length,P.C.B. mounted

FIG.1 --TYPICALFORWARDCHARACTERISTIC

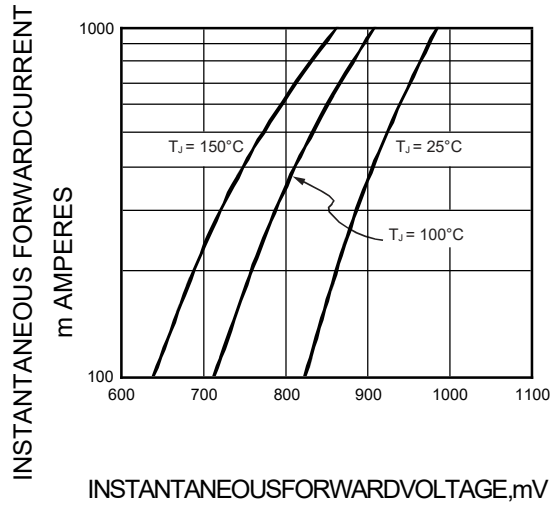


FIG.2 -- TYPICALJUNCTIONCAPACITANCE

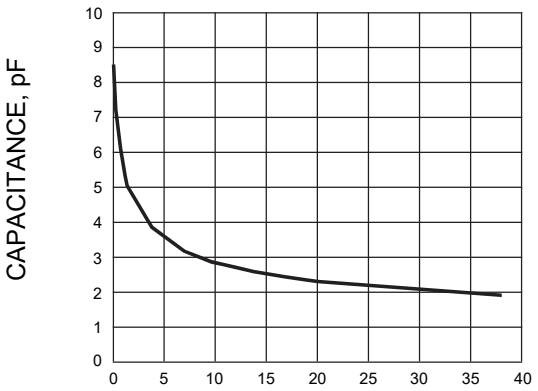


FIG.3 --TYPICAL INSTANTANEOUS REVERSE CHARACTERISTICS

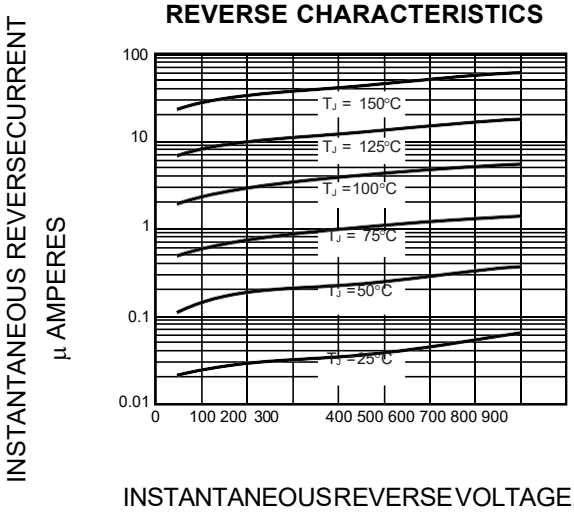
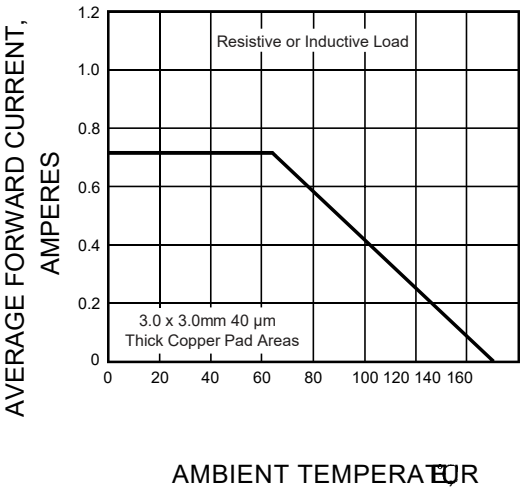
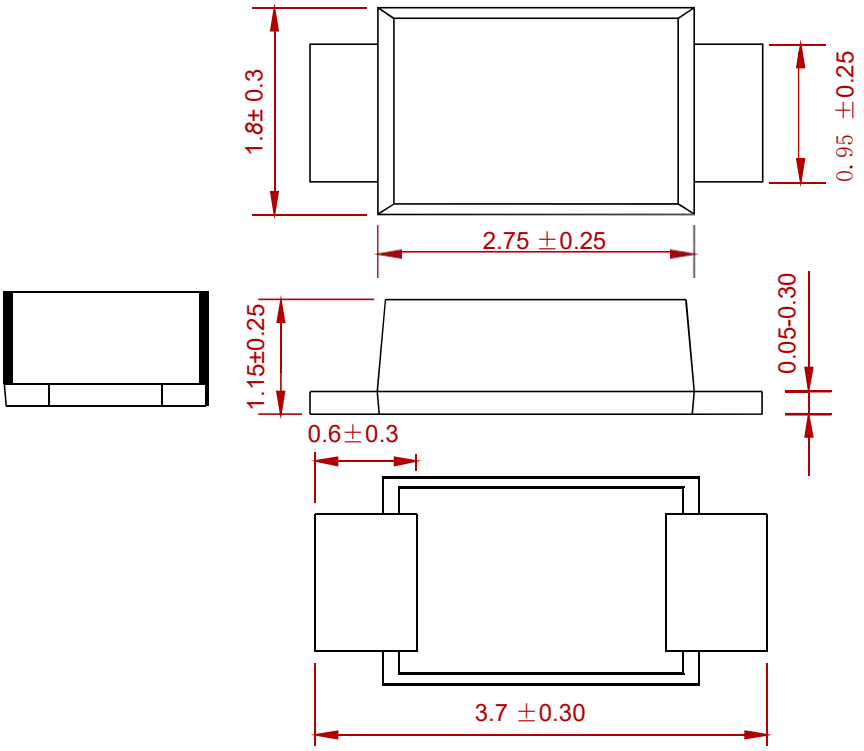


FIG.4 -- FORWARDDERATINGCURVE

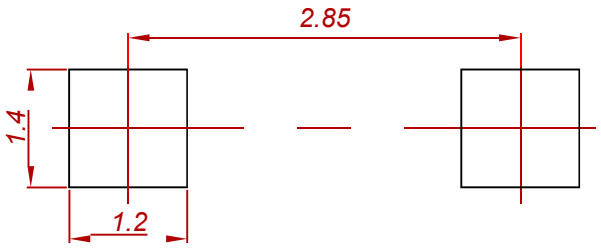


PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
SM4001PL THRU SM4007PL	SOD-123FL	3000

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